



#### SURFACE MOUNT SCHOTTKY BARRIER DIODE

### **Product Summary**

V <sub>R</sub> (V)	I <sub>F</sub> (mA)	V <sub>F MAX</sub> (V) @ +25°C	I <sub>R MAX</sub> (μΑ) @ +25°C
30V	200	0.575	150

### **Features and Benefits**

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- Low Capacitance
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Applications**

- SMPS
- · Free Wheeling Diodes
- Reverse Polarity Protection
- DC-DC Converters
- General Switching Applications

### **Mechanical Data**

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Dot
- Terminals: Finish NiPdAu Annealed over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 <sup>™</sup>
- Weight: 0.001 grams (Approximate)

#### X1-DFN1006-2





Top View

Bottom View

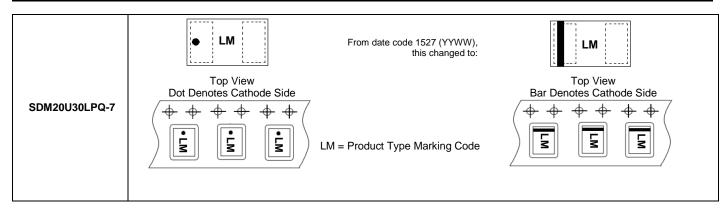
### Ordering Information (Note 5)

Device	Compliance	Packaging	Shipping
SDM20U30LPQ-7	Automotive	X1-DFN1006-2	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**





# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	30	٧
RMS Reverse Voltage		$V_{R(RMS)}$	21	V
Maximum (Peak) Forward Current		I <sub>F</sub>	200	mA
Peak Forward Surge Current	8.3ms Half Sine	I <sub>FSM</sub>	1.0	Α

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation	PD	250	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R <sub>0JA</sub>	400	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +125	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

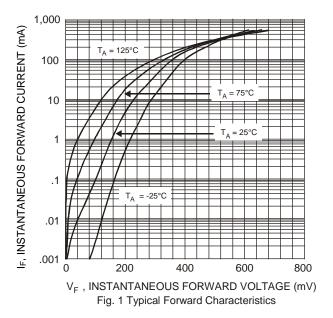
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	30	_	_	V	$I_R = 150 \mu A$
Forward Voltage Drop	V <sub>F</sub>	_	_	350 575	mV	I <sub>F</sub> = 20mA I <sub>F</sub> = 200mA
Peak Reverse Current (Note 7)	I <sub>R</sub>	_	_	150 30	μA μA	V <sub>R</sub> = 30V V <sub>R</sub> = 10V
Total Capacitance	C <sub>T</sub>	_	20	_	pF	$V_R = 0V$ , $f = 1.0MHz$
Reverse Recovery Time	t <sub>RR</sub>	_	3	_	ns	$I_F = I_R = 10 \text{mA}, I_{R(REC)} = 1 \text{mA},$ $R_L = 100 \Omega$

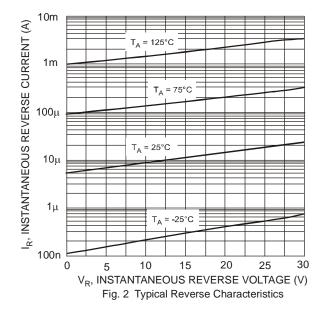
Notes:

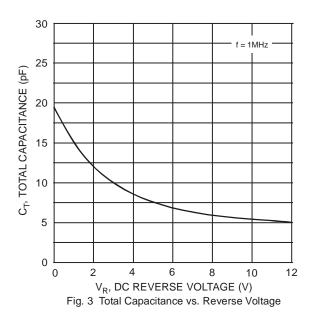
<sup>6.</sup> Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.

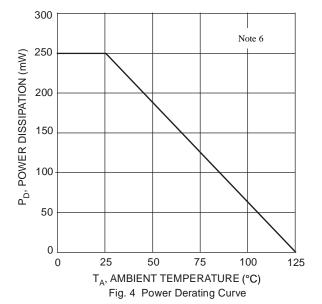
<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.









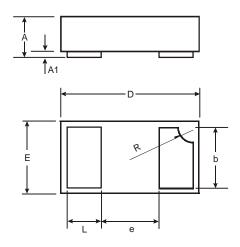




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X1-DFN1006-2

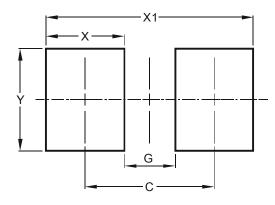


X1-DFN1006-2					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.40		
L	0.20	0.30	0.25		
R	0.05	0.15	0.10		
All	All Dimensions in mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X1-DFN1006-2



Dimensions	Value (in mm)		
С	0.70		
G	0.30		
Х	0.40		
X1	1.10		
Υ	0.70		



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